

Probe Tip Selection Guide

Probing	Model	Tip Radius	Tip Material	Shank	Shank Diameter	Overall Length	Comments
Small Geometry	DC - 11014	0.10 um	Tungsten	Nickel	20 mil (0.020")	35 mm (1.25")	Submicron probe for small feature probing, can easily be bent or cut to length
Small Geometry	DC - 11018	0.15 um	Tungsten	Nickel	20 mil (0.020")	35 mm (1.25")	Submicron probe for small feature probing, can easily be bent or cut to length
Small Geometry	DC - 11015	0.25 um	Tungsten	Nickel	20 mil (0.020")	35 mm (1.25")	Submicron probe for small feature probing, can easily be bent or cut to length
Small Geometry	DC - 11003	0.35 um	Tungsten	Nickel	20 mil (0.020")	35 mm (1.25")	Submicron probe for small feature probing, can easily be bent or cut to length
Small Geometry	DC - 11012	0.50 um	Tungsten	Nickel	20 mil (0.020")	35 mm (1.25")	Submicron probe for small feature probing, can easily be bent or cut to length
Small Geometry	DC - 11000	0.75 um	Tungsten	Nickel	20 mil (0.020")	35 mm (1.25")	Submicron probe for small feature probing, can easily be bent or cut to length
Small Geometry	DC - 11037	1.0 um	Tungsten	Nickel	20 mil (0.020")	35 mm (1.25")	Submicron probe for small feature probing, can easily be bent or cut to length
Small Geometry	DC - 11010	0.60 um	Tungsten	Tungsten	20 mil (0.020")	35 mm (1.25")	Submicron solid tungsten probe tip for small feature probing

Small Geometry	DC - 11029	0.75 um	Tungsten	Tungsten	20 mil (0.020")	35 mm (1.25")	Submicron solid tungsten probe tip for small feature probing
Small Geometry	DC - 11004	1.0 um	Tungsten	Tungsten	20 mil (0.020")	35 mm (1.25")	Solid tungsten probe for structures >4.0 um, general purpose probe
Small Geometry	DC - 11030	1.2 um	Tungsten	Tungsten	20 mil (0.020")	35 mm (1.25")	Solid tungsten probe for structures >5.0 um, general purpose probe
Small Geometry	DC - 11002	2.0 um	Tungsten	Tungsten	20 mil (0.020")	35 mm (1.25")	Solid tungsten probe for structures >8.0 um, general purpose probe
Small Geometry	DC - 11005	5.0 um	Tungsten	Tungsten	20 mil (0.020")	35 mm (1.25")	Solid tungsten probe for structures >20.0 um, general purpose probe
Bond Pads	DC - 11006	7.0 um	Tungsten	Tungsten	20 mil (0.020")	35 mm (1.25")	Solid tungsten probe for structures >30.0 um, general purpose probe
Bond Pads	DC - 11008	10.0 um	Tungsten	Tungsten	20 mil (0.020")	35 mm (1.25")	Solid tungsten probe for structures >40.0 um, general purpose probe
Bond Pads	DC - 11009	12.5 um	Tungsten	Tungsten	20 mil (0.020")	35 mm (1.25")	Solid tungsten probe for structures >50.0 um, general purpose probe
Bond Pads	DC - 11013	20.0 um	Tungsten	Tungsten	20 mil (0.020")	35 mm (1.25")	Solid tungsten probe for structures >80.0 um, general purpose probe
Bond Pads	DC - 11007	25.0 um	Tungsten	Tungsten	20 mil (0.020")	35 mm (1.25")	Solid tungsten probe for structures >100.0 um, general purpose probe

Bond Pads	DC - 11016	7.0 um	Gold Plated	Tungsten	20 mil (0.020")	35 mm (1.25")	Gold Plated solid tungsten probe for features > 30.0 um, reduced contact resistance, used to probe gold contacts/pads
Bond Pads	DC - 11031	10.0 um	Gold Plated	Tungsten	20 mil (0.020")	35 mm (1.25")	Gold Plated solid tungsten probe for features > 40.0 um, reduced contact resistance, used to probe gold contacts/pads
Bond Pads	DC - 11032	12.5 um	Gold Plated	Tungsten	20 mil (0.020")	35 mm (1.25")	Gold Plated solid tungsten probe for features > 50.0 um, reduced contact resistance, used to probe gold contacts/pads
Bond Pads	DC - 11033	15.0 um	Gold Plated	Tungsten	20 mil (0.020")	35 mm (1.25")	Gold Plated solid tungsten probe for features > 60.0 um, reduced contact resistance, used to probe gold contacts/pads
Bond Pads	DC - 11019	20.0 um	Gold Plated	Tungsten	20 mil (0.020")	35 mm (1.25")	Gold Plated solid tungsten probe for features > 80.0 um, reduced contact resistance, used to probe gold contacts/pads
Bond Pads	DC - 11034	25.0 um	Gold Plated	Tungsten	20 mil (0.020")	35 mm (1.25")	Gold Plated solid tungsten probe for features > 100.0 um, reduced contact resistance, used to probe gold contacts/pads
Bond Pads	DC - 11035	5.0 um	Tungsten Carbide	Tungsten Carbide	20 mil (0.020")	35 mm (1.25")	Tungsten Carbide probe for feature > 20.0 um, can be used for cutting & high temperature applications
Bond Pads	DC - 11020	7.5 um	Tungsten Carbide	Tungsten Carbide	20 mil (0.020")	35 mm (1.25")	Tungsten Carbide probe for feature > 30.0 um, can be used for cutting & high temperature applications
Bond Pads	DC - 11036	10.0 um	Tungsten Carbide	Tungsten Carbide	20 mil (0.020")	35 mm (1.25")	Tungsten Carbide probe for feature > 40.0 um, can be used for cutting & high temperature applications
Bond Pads	DC - 11021	12.5 um	Tungsten Carbide	Tungsten Carbide	20 mil (0.020")	35 mm (1.25")	Tungsten Carbide probe for feature > 50.0 um, can be used for cutting & high temperature applications

Bond Pads	DC - 11022	20.0 um	Tungsten Carbide	Tungsten Carbide	20 mil (0.020")	35 mm (1.25")	Tungsten Carbide probe for feature > 80.0 um, can be used for cutting & high temperature applications
Bond Pads	DC - 11023	25.0 um	Tungsten Carbide	Tungsten Carbide	20 mil (0.020")	35 mm (1.25")	Tungsten Carbide probe for feature > 100.0 um, can be used for cutting & high temperature applications
Bond Pads	DC - 11028	5.0 um	Beryllium Copper	Beryllium Copper	20 mil (0.020")	35 mm (1.25")	Solid Beryllium Copper probe for measurements requiring low contact resistance, soft material reduces pad damage
Bond Pads	DC - 11001	7.0 um	Beryllium Copper	Beryllium Copper	20 mil (0.020")	35 mm (1.25")	Solid Beryllium Copper probe for measurements requiring low contact resistance, soft material reduces pad damage
Bond Pads	DC - 11024	10.0 um	Beryllium Copper	Beryllium Copper	20 mil (0.020")	35 mm (1.25")	Solid Beryllium Copper probe for measurements requiring low contact resistance, soft material reduces pad damage
Bond Pads	DC - 11025	12.5 um	Beryllium Copper	Beryllium Copper	20 mil (0.020")	35 mm (1.25")	Solid Beryllium Copper probe for measurements requiring low contact resistance, soft material reduces pad damage
Bond Pads	DC - 11026	20.0 um	Beryllium Copper	Beryllium Copper	20 mil (0.020")	35 mm (1.25")	Solid Beryllium Copper probe for measurements requiring low contact resistance, soft material reduces pad damage
Bond Pads	DC - 11027	25.0 um	Beryllium Copper	Beryllium Copper	20 mil (0.020")	35 mm (1.25")	Solid Beryllium Copper probe for measurements requiring low contact resistance, soft material reduces pad damage